

- ✎ 125: (3060559) {organic polymer\$6 polyimide\$4 co adj} polymers\$4 copolym
- ✎ 126: (12353236) {polymer\$6 polyimide\$4 co adj} polymers\$4 copolymers\$4 cop
- ✎ 127: (3103963) 26 16
- ✎ 128: (123647) {bond ball bump} adj {pad}
- ✎ 129: (421 27 adj) 26
- ✎ 130: (119) 29 and 16
- ✎ 131: (101 36 and 1
- ✎ 132: (1) 29 and 1
- ✎ 133: (1749531) adhes\$6
- ✎ 134: (1261 29 and 33
- ✎ 135: (1261 34 and 24
- ✎ 136: (1261 35 and 27
- ✎ 137: (2061) prob\$4 adj pad
- ✎ 138: (1121 27 near 2 37
- ✎ 139: (115) 15 and 24
- ✎ 140: (11201) 28 near 6 33
- ✎ 141: (7) 40 same 1
- ✎ 142: (1157686) {multi\$4 multiplicit\$3 plural\$4 dual} adj {layer film} multi
- ✎ 143: (1196) 29 near 42
- ✎ 144: (11221 43 and 6
- ✎ 145: (12000) 33 with 28
- ✎ 146: (115) 44 and 45
- ✎ 147: (151503) die
- ✎ 148: (1901 8 15 30 36 46
- ✎ 149: (1391 47 and 48

43 and 6

U	I	Inventor	Document	Issued	P	Title	Current	Current X	Retrieval	S	C	P	S	Image	Doc P
1		Yin, Lang	US 2003000	2003	12	Wire bonded microelectronic device	438/10	257/E21.51							US 20030
2		Yu, Chen-H	US 670328	2004	6	Metal bond pad for low-k inter metal di	438/40	257/780;							US 670328
3		Martin, J. Sc	US 2004000	2004	2	USE OF AMORPHOUS ALUMINUM OXIDE ON	257/29	257/E21.0							US 20040
4		Akhsan, Mo	US 2004000	2004	16	Edge-sealed substrates and methods f	438/12								US 20040
5		Fehr, Beral	US 2004000	2004	9	Method for stack-packaging integrate	438/10	257/E25.0							US 20040
6		Akram, Sal	US 2004000	2004	15	Semiconductor package with stacked	438/10	257/E21.70							US 20040
7		Downey, Su	US 2004000	2004	6	Semiconductor device having a wire bo	257/75	257/762;							US 20040
8		Gleason, Jef	US 2004000	2004	14	Nickel bonding cap over copper metaliz	257/45								US 20040
9		Batra, Shub	US 200302	2003	13	Method and structures for reduced par	261/48	257/E23.0							US 20030
10		Batra, Shub	US 200302	2003	12	Method and structures for reduced par	257/75	257/E23.0							US 20030